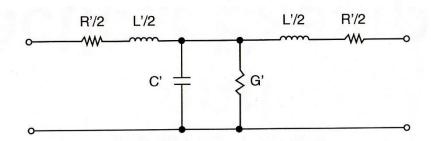
CIRCUIT DIAGRAM OF A TRANSMISSION LINE

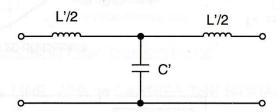


- L' CHARACTERISTIC INDUCTANCE PER UNIT LENGTH nH/cm
- C' CHARACTERISTIC CAPACITANCE PER UNIT LENGTH pF/cm
- R' CHARACTERISTIC RESISTANCE PER UNIT LENGTH Ω /cm
- G' CHARACTERISTIC CONDUCTANCE PER UNIT LENGTH S/cm

LINE IMPEDANCE
$$\overrightarrow{Zo} = \sqrt{\frac{j\omega L' + R'}{j\omega C' + G'}}$$

LOSS-FREE TRANSMISSION LINES

ON PRINTED CIRCUIT BOARDS IN DIGITAL SYSTEMS THE LOSSES OF THE LINE CAN BE NEGLECTED:



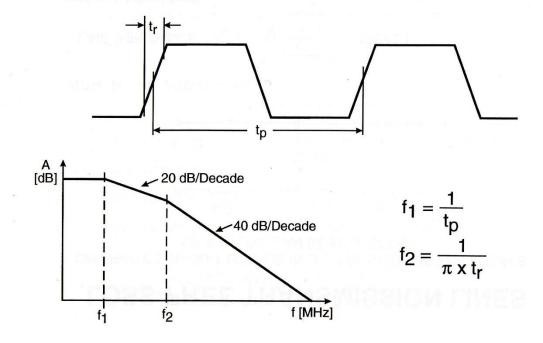
WITH R' \rightarrow 0 AND G' \rightarrow 0:

LINE IMPEDANCE :
$$Z_0 = \sqrt{\frac{L'}{C'}}$$
 (REAL!)

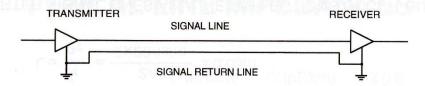
PROPAGATION TIME
$$T = \sqrt{L'xC'}$$

CUT-OFF FREQUENCY: fo =
$$\frac{1}{2\pi\sqrt{L'xC'}}$$
 WITH L',C' \rightarrow 0 \Rightarrow fg = ∞

FREQUENCY SPECTRUM OF DIGITAL SIGNALS



TRANSMISSION LINE



A TRANSMISSION LINE CONSISTS OF

- A SIGNAL LINE, WHICH CARRIES THE SIGNAL CURRENT
- A SIGNAL RETURN LINE (MOSTLY GND) WHICH CARRIES A RETURN CURRENT OF THE SAME MAGNITUDE.

ANY DC INTERCONNECT BETWEEN THE GND TERMINALS OF THE TWO CIRCUITS (e.g. SAFETY EARTH) WILL NOT PROVIDE A SIGNAL RETURN PATH ACCORDING TO THE TRANSMISSION LINE THEORY.

THE AREA BETWEEN THE SIGNAL LINE AND THE RETURN LINES DETERMINES THE CAPABILITY OF THE CIRCUIT TO RADIATE RF AND ALSO ITS IMMUNITY AGAINST EMI.

TRANSMISSION LINE THEORY

RULE OF THUMB:

THE TRANSMISSION LINE THEORY HAS TO BE APPLIED WHEN THE RISE TIME OF THE SIGNAL IS SHORTER THAN TWICE THE PROPAGATION TIME.

EXAMPLE 1: TWISTED PAIR CABLE; $\tau = 5 \text{ ns/m}$; $t_r = 2 \text{ ns}$

$$L = \frac{t_r}{2\tau} = \frac{2 \text{ ns}}{2 \times 5 \text{ ns/m}} = 0.2 \text{ m}$$

EXAMPLE 2: BUS LINE; $\tau = 20 \text{ ns/m}$; $t_r = 2 \text{ ns}$

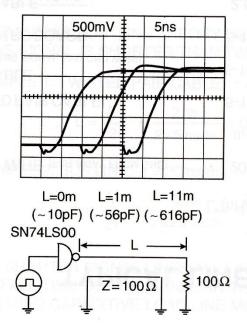
$$L = \frac{t_r}{2\tau} = \frac{2 \text{ ns}}{2 \times 20 \text{ ns/m}} = 0.05 \text{m}$$

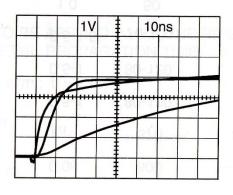
WITH SHORTER SIGNAL LINES ALL LINE REFLECTIONS OCCUR DURING THE RISE/FALL TIME OF THE SIGNAL. IN THIS CASE IT IS ALLOWED TO USE THE SIMPLIFIED CAPACITIVE LOAD LINE MODEL.

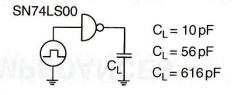
TYPICAL LINE IMPEDANCES

	L' (nH/cm)	C' (pF/cm)	$Z(\Omega)$	τ (ns/m)
SINGLE WIRE (FAR AWAY FROM GND)	20	0.06	600	~4
SPACE	μ_{O}	$\epsilon_{ m O}$	370	3,3
TWISTED PAIR CABLE	5-10	0.5-1	80-120	5
FLAT CABLE (ALTERNATING SIGNAL AND GND WIRE)	5-10	0.5-1	80-120	5
WIREONPCBOARD	5-10	0.5-1.5	70-100	~5
COAXCABLE	2,5	1.0	50	5
BUSLINE	5-10	10-30	20-40	10-20

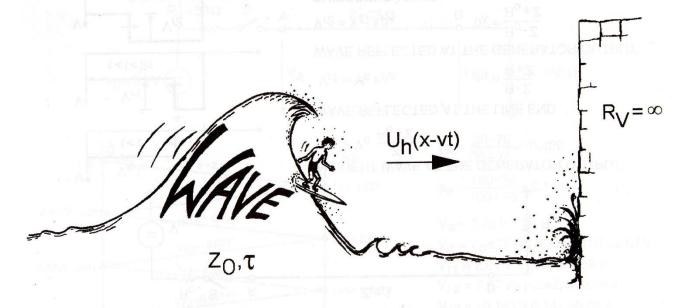
WAVEFORMS WITH TRANSMISSION LINE AND CAPACITIVE LOAD





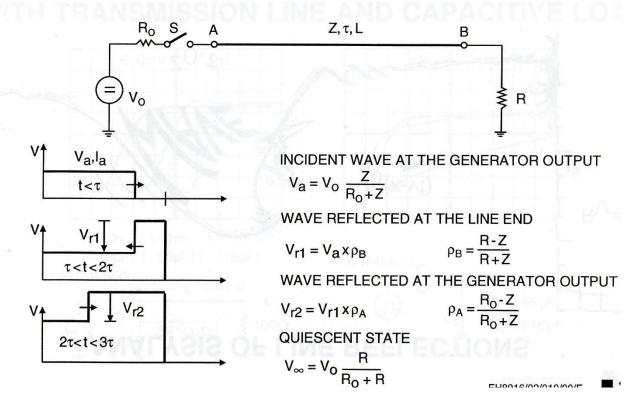


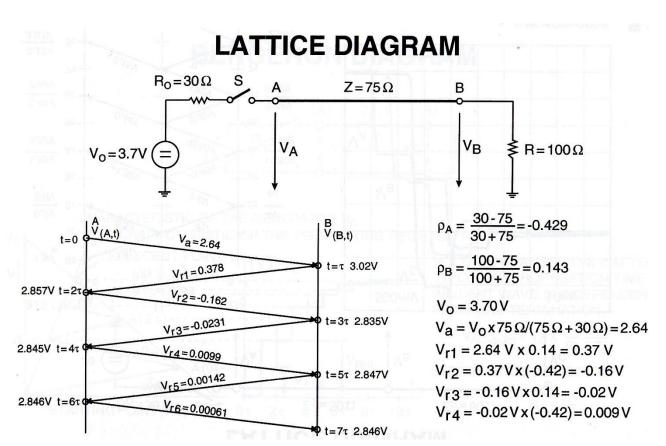
ANALYSIS OF LINE REFLECTIONS



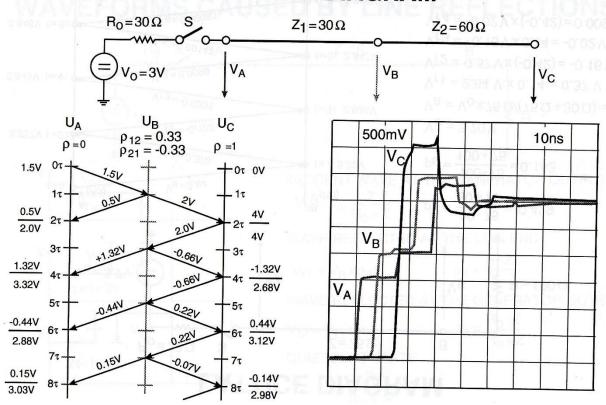
WAY ELURING CAUSED BY LINE REFLECTIONS

WAVEFORMS CAUSED BY LINE REFLECTIONS

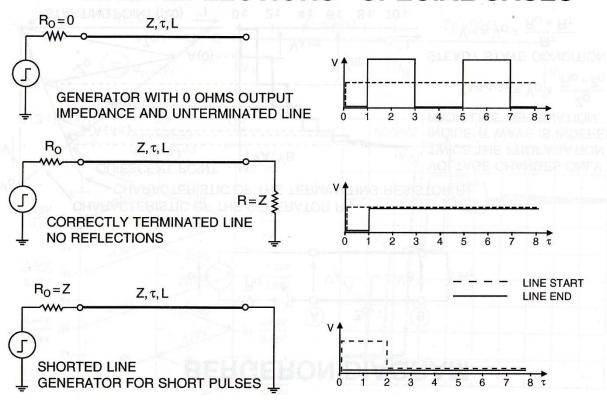




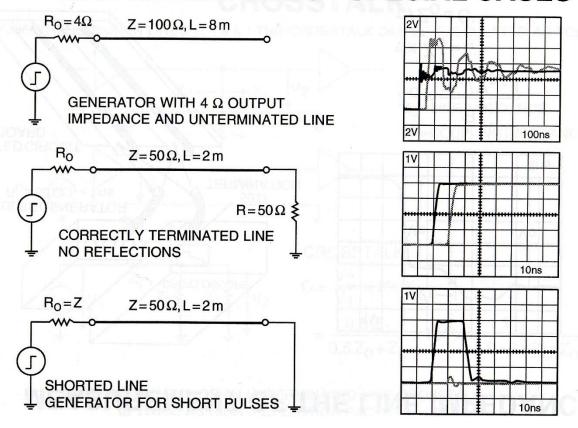
LATTICE DIAGRAM



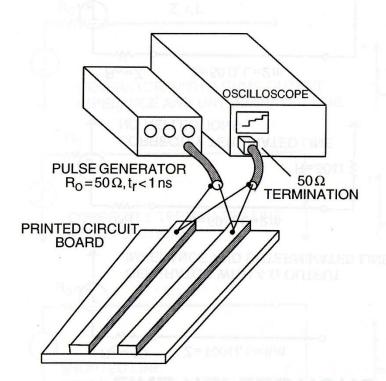
LINE REFLECTIONS - SPECIAL CASES

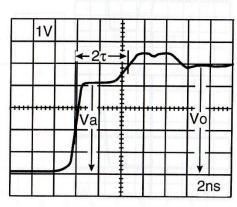


LINE REFLECTIONS - SPECIAL CASES



MEASUREMENT OF THE LINE IMPEDANCE





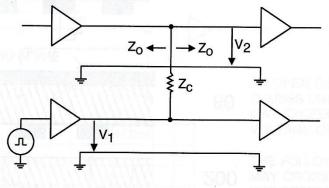
$$Z_{O} = \frac{R_{O}^{*)}}{V_{O}/V_{a}-1}$$
$$\tau \times Z_{O} = L'$$

$$\tau/Z_0 = C'$$

*) NOTE: $R_0 = 50 \Omega // 50 \Omega = 25 \Omega$

CROSSTALK

ON LONG TRANSMISSION LINES (2 τ > t_{r}) THE CROSSTALK CAN BE CALCULATED AS FOLLOWS:



 Z_0 = LINE IMPEDANCE Z_C = COUPLING IMPEDANCE

CROSSTALK:

$$C = \frac{V_2}{V_1} \times 100\%$$

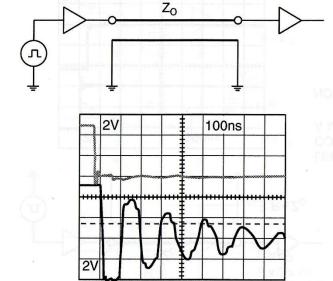
$$= \frac{0.5 Z_0}{0.5 Z_0 + Z_C} \times 100\% = \frac{1}{1 + 2 \times Z_C / Z_0} \times 100\%$$

NOTE: AT THE END OF AN UNTERMINATED LINE CROSSTALK
IS TWICE AS HIGH (REFLECTION FACTOR p = 1)!

CROSSTALK ON PRINTED CIRCUIT BOARDS (TYPICAL VALUES)

	LINE IMPEDANCE $Z_0 [\Omega]$	COUPLING IMPEDANCE $Z_{\mathbb{C}}[\Omega]$	CROSSTALK [%]
	200	100	50
GND PLANE	80	125	25 BEDVICE
	7 100	400	va 11 rows:
Note	ance	110/02/019/00/E	

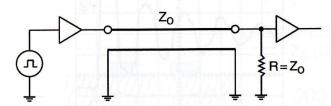
OPEN CIRCUIT

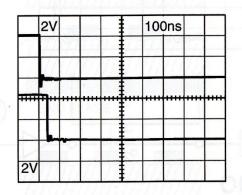


AN OPEN CIRCUIT AT THE LINE END CAUSES UNDER- AND OVERSHOOTS WHICH MAY EXCEED THE MAXIMUM RATED INPUT VOLTAGE OF THE RECEIVING CIRCUIT.

THE FOLLOWING OVER- AND UNDERSHOOTS MAY CROSS THE THRESHOLD VOLTAGE OF THE RECEIVER SEVERAL TIMES AND MAY GENERATE SYSTEM ERRORS.

LINE REFLECTIONS TERMINATED LINE



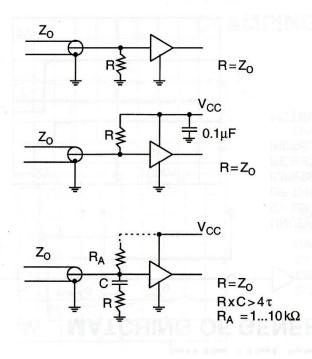


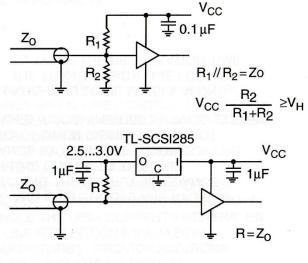
LINE REFLECTIONS ARE ELIMINATED BY A CORRECT LINE TERMINATION.
A MISMATCH UP TO 50% IS ACCEPTABLE.

NOTE: - INCREASED POWER DISSIPATION

- HIGH DRIVE CAPABILITY REQUIRED.

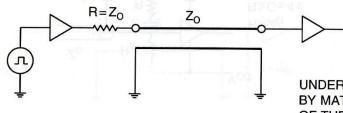
LINE TERMINATION CIRCUITS

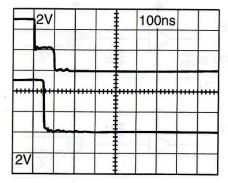




MISMATCH OF 50%...100% ACCEPTABLE (WITH LOW IMPEDANCE BUS LINES UP TO 400%).

LINE REFLECTIONS MATCHING OF GENERATOR IMPEDANCE

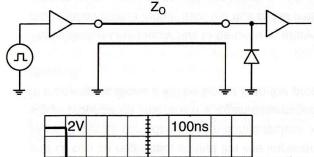




UNDER- AND OVERSHOOTS ARE AVOIDED BY MATCHING THE OUTPUT IMPEDANCE OF THE LINE DRIVER TO THE LINE IMPEDANCE BY MEANS OF A SERIES RESISTOR. POWER DISSIPATION IS NOT INCREASED (RECOMMENDED IN CMOS SYSTEMS).

NOTE: UNDEFINED LOGIC LEVELS ALONG
THE TRANSMISSION LINE FOR UP
TO TWICE THE PROPAGATION TIME.

LINE REFLECTIONS CLAMPING DIODES



2V 100ns 2V 2V

CLAMPING DIODES AT THE END OF THE TRANSMISSION LINE ABSORBE THE ENERGY OF UNDER- AND OVERSHOOTS AND ENSURE A CLEAN SIGNAL WAVEFORM. INPUT CIRCUITS OF LOGIC IC'S CONTAIN THESE CLAMPING DIODES.

NOTE: THE CLAMPING DIODES OF VLSI CIRCUITS ARE OFTEN NOT CAPABLE TO HANDLE THE HIGH CURRENTS GENERATED BY LINE REFLECTIONS (PARASITIC TRANSISTORS!) . PROVIDE ADDITIONAL SCHOTTKY CLAMPING DIODES!